

ABSTRACT

In a method of manufacturing a circuit forming board, a first sheet having a first direction is transferred in a second direction, so that the first direction of the first sheet is parallel to the second direction. Films are stuck onto both surfaces of the first sheet while transferring the first sheet in a third direction orthogonal to the first direction of the first sheet. This method allows connecting member, such as conductive paste, to electrically coupling between layers of the circuit forming board.